

AMENDMENTS TO THE CLAIMS

1. (Withdrawn)
2. (Withdrawn)
3. (Withdrawn)
4. (Withdrawn))
5. (Withdrawn)
6. (Withdrawn)
7. (Withdrawn)
8. (Withdrawn)
9. (Withdrawn)
10. (Withdrawn)

11. (Currently Amended) In a device An apparatus having at least one sealed microchannels microchannel therein, the improvement comprising:
a first substrate,
at least one etched microchannel in said first substrate,
a second substrate positioned on said first substrate that covers said at
least one etched microchannel in said first substrate,
a corresponding at least one annealed microchannel in said second
substrate immediately above said at least one microchannel in said first
substrate, and
a bond connecting said first substrate and said second substrate, wherein
said at least one etched microchannel and said at least one annealed
microchannel comprise said at least one the sealed microchannels microchannel
having a curved configuration.

12. (Currently Amended) The improvement apparatus of Claim 11, wherein said at least one sealed microchannels have microchannel has no sharp corners therein.

13. (Currently Amended) The improvement apparatus of Claim 11, wherein said curved configuration is at least one etched microchannel in said first substrate and said corresponding at least one annealed microchannel in said second substrate form a circular at least one sealed microchannel.

14. (Currently Amended) The device apparatus of Claim 11, wherein said sealed microchannels are located with a plurality of bonded members first substrate is selected from the group consisting of glass members, glass and silicon members, glass and polymer members, and members selected from the group of glass, silicon and polymers.

15. (Currently Amended) The device apparatus of Claim 14 11, wherein said members are composed of glass bonded together by either bond comprises fusion or anodic bonding, and annealed at a temperature for a time period sufficient to create the curved configuration of the at least one sealed microchannel therein.

16. (Currently Amended) The device apparatus of Claim 15 11, fabricated by annealing the bonded members at a temperature of 200° to 800° C for a time period of 2 to 24 hrs wherein said second substrate is selected from the group consisting of glass members, glass and silicon members, glass and polymer members, and members selected from the group of glass, silicon and polymers.